

Part Number: XZMYK56W

3.0mmx1.0 mm RIGHT ANGLE SMD CHIP LED LAMP

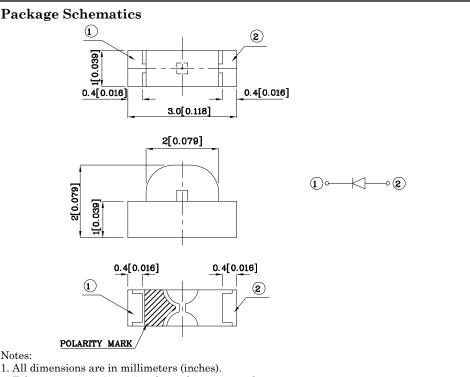
Features

- Ideal for indication light on hand held products
- Long life and robust package
- Standard Package: 2,000pcs/ Reel
- MSL (Moisture Sensitivity Level): 3
- RoHS compliant





ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES



2. Tolerance is $\pm 0.15(0.006")$ unless otherwise noted.

3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)		Yellow (AlGaInP)	Unit	
Reverse Voltage V		5	V	
Forward Current	$I_{\rm F}$	30	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	$i_{\rm FS}$	175	mA	
Power Dissipation	\mathbf{P}_{D}	75	mW	
Operating Temperature	TA	-40 ~ +85	°C	
Storage Temperature	Tstg	-40 ~ +85		

A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

Operating Characteristics (T _A =25°C)	Yellow (AlGaInP)	Unit	
Forward Voltage (Typ.) (I _F =20mA)	V_{F}	2	V
Forward Voltage (Max.) (I _F =20mA)	V_{F}	2.5	V
Reverse Current (Max.) (V _R =5V)	I_R	10	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =20mA)	λР	590*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I _F =20mA)	λD	590*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	$ riangle \lambda$	20	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	20	pF

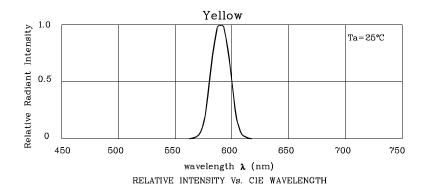
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity CIE127-2007* (IF=20mA) mcd		Wavelength CIE127-2007* nm λP	Viewing Angle 20 1/2
				min.	typ.		
XZMYK56W	Yellow	AlGaInP	Water Clear	80*	148*	590*	120°

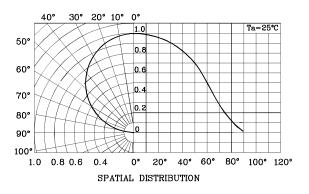
*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

Sep 22,2016

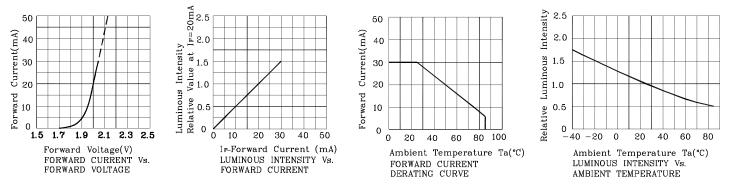
XDSA1476 V9-Z Layout: Maggie L.



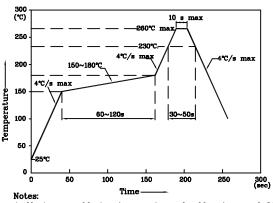




Yellow



LED is recommended for reflow soldering and soldering profile is shown below.



Reflow Soldering Profile for SMD Products (Pb-Free Components)

1. Maximum soldering temperature should not exceed 260°C

2. Recommended reflow temperature: 145°C-260°C 3. Do not put stress to the epoxy resin during

high temperatures conditions



✤ The device has a single mounting surface. The device must be mounted according to the specifications.

CHIP LED LAMP

Recommended Soldering Pattern

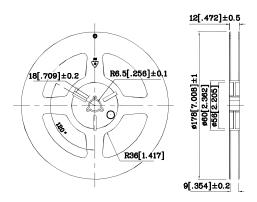
3.0mmx1.0 mm RIGHT ANGLE SMD

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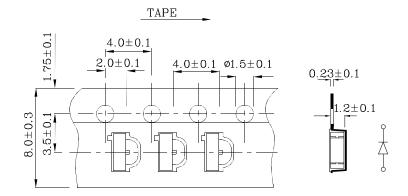
(Units : mm; Tolerance: ± 0.1)



Reel Dimension



Tape Specification (Units : mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm

2. Luminous intensity / luminous flux: +/-15%

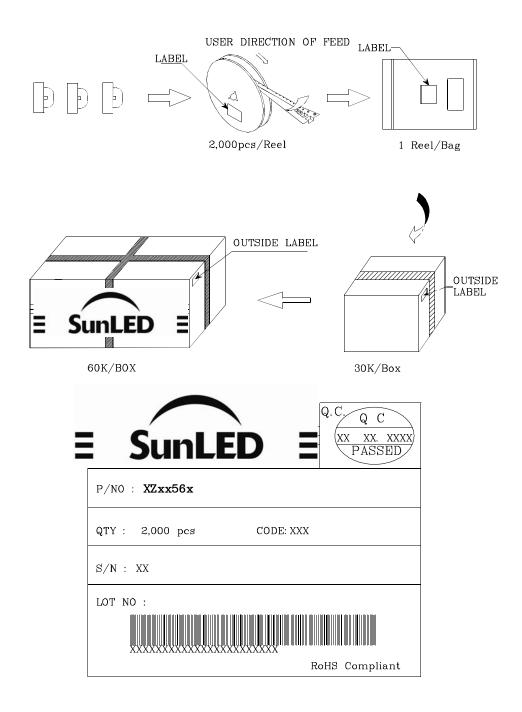
3. Forward Voltage: +/-0.1V $\,$

Note: Accuracy may depend on the sorting parameters.

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PACKING & LABEL SPECIFICATIONS



TERMS OF USE

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- 2. Contents within this document are subject to improvement and enhancement changes without notice.
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- User accepts full risk and responsibility when operating the product(s) beyond their intended specifications. 4. The product(s) described in this document are intended for electronic applications in which a person's life is not reliant upon the LED. Please
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